



520.45782X00

IPW

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: NAKATSUKA, et al.

Serial No.: 10/562,725

Filed: 5/23/2006

Title: Reflow Soldering Method Using Pb-free Solder Alloy, and Hybrid Mounting Method and Structure

Art Unit: 1793

Examiner: Stoner, K.

Conf. No.: 1307

INFORMATION DISCLOSURE STATEMENT
UNDER 37 CFR 1.97 & 1.98

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In the matter of the above-identified application, applicants are submitting herewith a copy of a communication from a foreign patent office in a counterpart foreign application and copies of the documents, other than the U.S. documents, listed in the attached form equivalent to Form PTO/SB/08A for the Examiner's consideration.

This information disclosure statement is being submitted before the mailing date of a first office action on the merits.

To the extent the documents listed on the attached form equivalent to PTO/SB/08A and PTO/SB/08B are not in the English language, the requirement of 37 CFR 1.98(a)(3) for a concise explanation of the relevance is satisfied by an English abstract.

US Patent No. 5,526,370 a member of the same patent family as JP 08-187591.

US Patent No. 6,585,149 a member of the same patent family as 2003-46229.

It is respectfully requested that this information disclosure statement be considered by the Examiner.

Please charge any shortage in the fees due in connection with the filing of this paper, including excess claim fees, to Deposit Account No. 01-2135 (520.45782X00), and please credit any excess fees to such deposit account.

Respectfully submitted,

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